# UNISONIC TECHNOLOGIES CO., LTD

1N50-TA **Power MOSFET** 

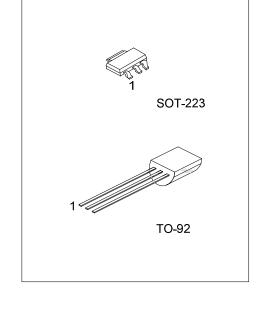
## **1.0A, 500V N-CHANNEL POWER MOSFET**

#### DESCRIPTION

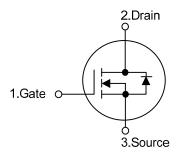
The UTC 1N50-TA is a high voltage MOSFET and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and have a high rugged avalanche characteristics. This power MOSFET is usually used at high speed switching applications in power supplies, PWM motor controls, high efficient DC to DC converters and bridge circuits.

## **FEATURES**

- \*  $R_{DS(ON)}$  < 10.5 $\Omega$  @  $V_{GS}$ =10V,  $I_{D}$ =0.5A
- \* Fast switching capability
- \* Avalanche energy specified
- \* Improved dv/dt capability, high ruggedness



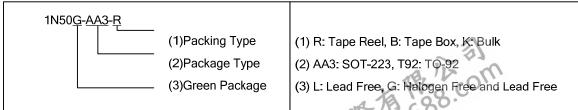
#### **SYMBOL**



#### ORDERING INFORMATION

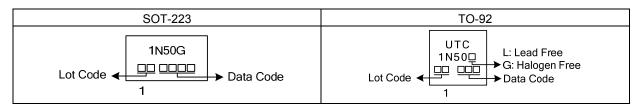
Ordering Number		Daakaga	Pin Assignment			Dooking	
Lead Free	Halogen Free	Package	1	2	3	Packing	
-	1N50G-AA3-R	SOT-223	G	D	S	Tape Reel	
1N50L-T92-B	1N50G-T92-B	TO-92	G	D	S	Tape Box	
1N50L-T92-K	1N50G-T92-K	TO-92	G	D	S	Bulk	

Note: Pin Assignment: G: Gate D: Drain S: Source



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## **MARKING**



## ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT	
Drain-Source Voltage		V <sub>DSS</sub> 500		V	
Gate-Source Voltage		$V_{GSS}$	±30	V	
Drain Current	Continuous	I <sub>D</sub> 1.0		Α	
	Pulsed (Note 2)	I <sub>DM</sub>	4.0	Α	
Avalanche Energy	Single Pulsed (Note 3)	E <sub>AS</sub>	10	mJ	
Peak Diode Recovery dv/dt (Note 4)		dv/dt	5.0	V/ns	
Power Dissipation	SOT-223		7.8	W	
	TO-92	P <sub>D</sub>	1.42	W	
Junction Temperature		TJ	+150	°C	
Storage Temperature		T <sub>STG</sub>	-55 ~ +150	°C	

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. L = 10mH,  $I_{AS}$  = 1.4A,  $V_{DD}$  = 50V,  $R_G$  = 25 $\Omega$ , Starting  $T_J$  = 25 $^{\circ}$ C
- 3.  $I_{SD} \le 1.0 A$ , di/dt  $\le 200 A/\mu s$ ,  $V_{DD} \le BV_{DSS}$ , Starting  $T_J = 25 ^{\circ}C$

## **THERMAL DATA**

PARAMETER		SYMBOL	RATINGS	UNIT	
Junction to Ambient	SOT-223	0	150	°C/W	
	TO-92	θ <sub>JA</sub>	180	°C/W	
Junction to Case	SOT-223	Өлс	16	°C/W	
	TO-92		88	°C/W	



**Power MOSFET** 

## **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C, unless otherwise specified)

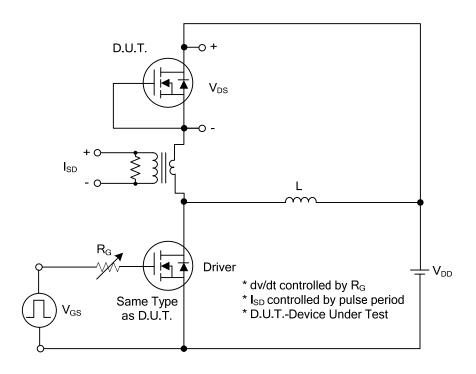
PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT		
OFF CHARACTERISTICS									
Drain-Source Breakdown Voltage		BV <sub>DSS</sub>	$V_{GS}$ =0 $V$ , $I_D$ =250 $\mu$ A	500			V		
Drain-Source Leakage Current		I <sub>DSS</sub>	V <sub>DS</sub> =500V, V <sub>GS</sub> =0V			1	μA		
Gate-Source Leakage Current	Forward	1	$V_{GS}$ =30V, $V_{DS}$ =0V			100	nA		
	Reverse	I <sub>GSS</sub>	V <sub>GS</sub> =-30V, V <sub>DS</sub> =0V			-100	nA		
ON CHARACTERISTICS									
Gate Threshold Voltage		$V_{GS(TH)}$	$V_{DS}=V_{GS}$ , $I_D=250\mu A$	3.0		5.0	V		
Static Drain-Source On-State Resistance		R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =0.5A			10.5	Ω		
DYNAMIC CHARACTERISTICS									
Input Capacitance	out Capacitance				86		pF		
Output Capacitance		Coss	$V_{GS}$ =0V, $V_{DS}$ =25V, f=1MHz		17		pF		
Reverse Transfer Capacitance		$C_{RSS}$			5.0		pF		
SWITCHING CHARACTERISTICS									
Total Gate Charge (Note 1)		$Q_G$	V <sub>DS</sub> =30V, V <sub>GS</sub> =10V, I <sub>D</sub> =0.5A,		8.8		nC		
Gate to Source Charge		$Q_{GS}$	$I_{G}=100\mu A$ (Note 1, 2)		1.2		nC		
Gate to Drain Charge		$Q_{GD}$	IG-100μΑ (Note 1, 2)		1.3		nC		
Turn-on Delay Time (Note 1)		t <sub>D(ON)</sub>			32		ns		
Rise Time		$t_{R}$	$V_{DD}$ =30V, $V_{GS}$ =10V, $I_{D}$ =0.5A,		10		ns		
Turn-off Delay Time		t <sub>D(OFF)</sub>	R <sub>G</sub> =25Ω (Note 1, 2)		33		ns		
Fall-Time		$t_{F}$			17		ns		
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS									
Maximum Body-Diode Pulsed Current		Is				1.0	Α		
Drain-Source Diode Forward Voltage (Note 1)		I <sub>SM</sub>				4.0	Α		
Maximum Body-Diode Continuous Current		$V_{SD}$	I <sub>S</sub> =0.3A, V <sub>GS</sub> =0V			1.4	V		
Reverse Recovery Time (Note 1)		t <sub>rr</sub>	I <sub>S</sub> =1.0A, V <sub>GS</sub> =0V,		200		ns		
Reverse Recovery Charge		$Q_{rr}$	dI <sub>F</sub> /dt=100A/μs		0.4		μC		

Notes: 1. Pulse Test: Pulse width ≤ 300µs, Duty cycle ≤ 2%.

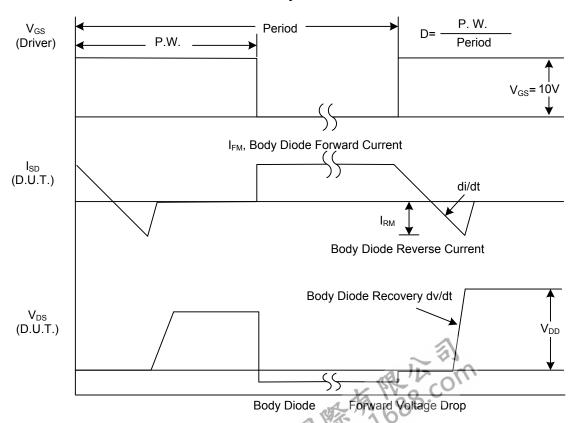


<sup>2.</sup> Essentially independent of operating temperature.

## **■ TEST CIRCUITS AND WAVEFORMS**



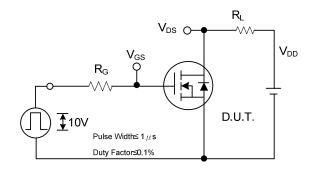
## Peak Diode Recovery dv/dt Test Circuit

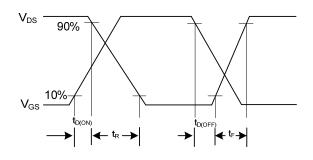


Peak Diode Recovery dv/dt Waveforms

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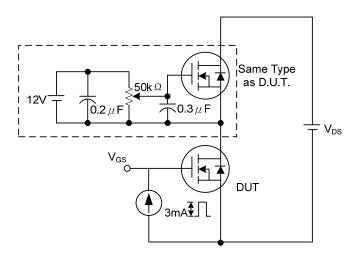
## **TEST CIRCUITS AND WAVEFORMS (Cont.)**

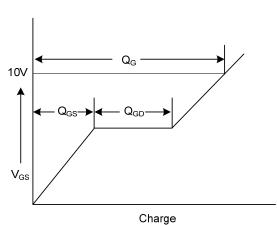




**Switching Test Circuit** 

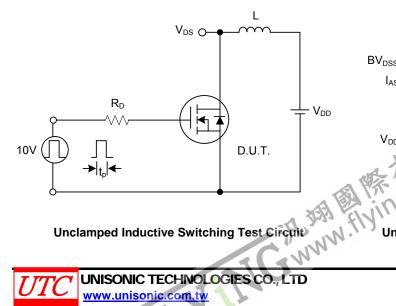
**Switching Waveforms** 

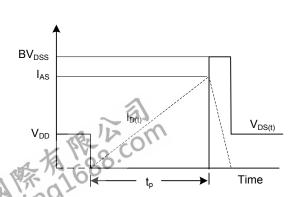




**Gate Charge Test Circuit** 

**Gate Charge Waveform** 





**Unclamped Inductive Switching Waveforms** 

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